PNZ108CL (PN108CL)

Silicon planar type

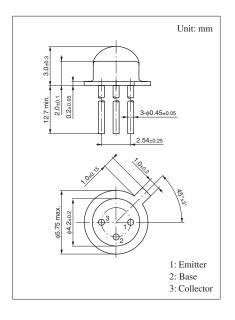
For optical control systems

■ Features

- High sensitivity: $I_{CE(L)} = 3.5 \text{ mA (min.)}$
- Wide directivity characteristics for easy use
- Fast response: $t_r = 5 \mu s$ (typ.)
- Signal mixing capability using base pin
- Small size (low in height) package

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit	
Collector-emitter voltage (Base open)	V _{CEO}	20	V	
Collector-base voltage (Emitter open)	V _{CBO}	30	V	
Emitter-collector voltage (Base open)	V _{ECO}	3	V	
Emitter-base voltage (Collector open)	V_{EBO}	5	V	
Collector current	I_C	20	mA	
Collector power dissipation *	P _C	100	mW	
Operating ambient temperature	T_{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to +100	°C	



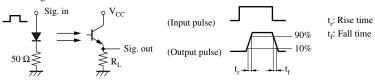
■ Electrical-Optical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Photocurrent *1, *2	I _{CE(L)}	$V_{CE} = 10 \text{ V}, L = 500 \text{ lx}$	3.5			mA
Dark current	I_{CEO}	$V_{CE} = 10 \text{ V}$		0.05	2.00	μΑ
Peak emission wavelength	λ_{p}	$V_{CE} = 10 \text{ V}$		900		nm
Half-power angle	θ	The angle from which photocurrent		80		0
		becomes 50%				
Rise time *3	t _r	$V_{CC} = 10 \text{ V}, I_{CE(L)} = 5 \text{ mA}, R_L = 100 \Omega$		5		μs
Fall time *3	$t_{\rm f}$			6		μs
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_{CE(L)} = 1 \text{ mA}, L = 1000 \text{ lx}$		0.3	0.6	V

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
 - 2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.
 - 3. This device is designed be disregarded radiation.
 - 4. *1: Source: Tungsten (color temperature 2856 K)
 - *2: Rank classification

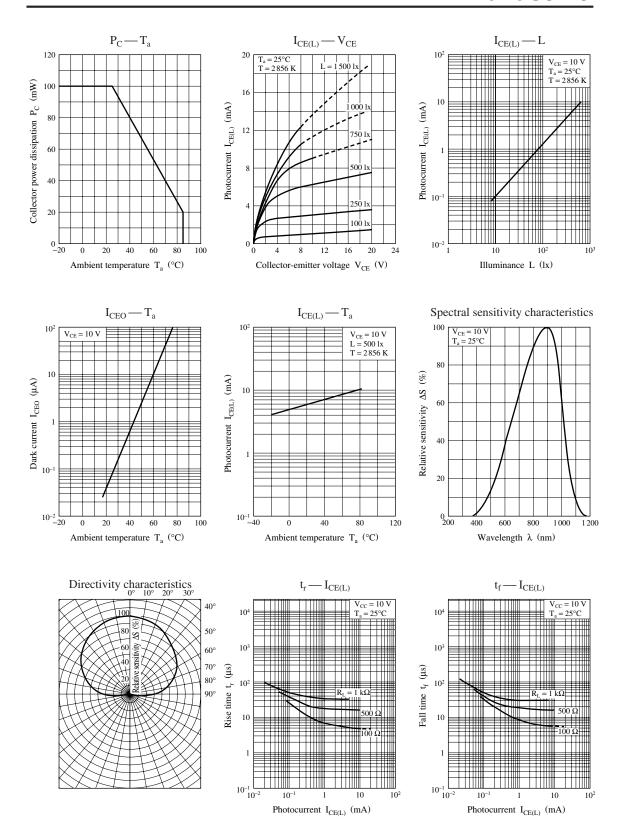
Rank	Q	R	S	No-rank
$I_{CE(L)}$ (mA)	3.5 to 6.0	5.0 to 9.1	>7.5	>3.5

*3: Switching time measurement circuit



Note) The part number in the parenthesis shows conventional part number.

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